

ABSTRACT

The present invention provides a bonding apparatus and bonding method which can prevent warping of substrates by ensuring a sufficient standing time following bonding of the substrates, using a simple and compact apparatus. Substrate carrying parts 1a are formed along the circumference of a rotating turntable 1. The respective substrate carrying parts 1a are formed so that these parts pass through substrate placement positions 11 and 12, a bonding position 13, pre-curing standing positions 14a through 14d, a curing position 15, a post-curing standing position 16 and a conveying position 17 as the turntable 1 rotates. After being bonded in the bonding position 13, the substrates move through the pre-curing standing positions 14a through 14d as a result of the rotation of the turntable 1, and are allowed to stand for a fixed period of time, so that warping is corrected.